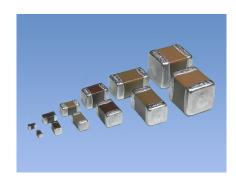


KYOCERa

How to Order



■Features

- •Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications.
- •We have a network worldwide in order to supply our global customer bases quickly and efficiently.
- •All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- •Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and superior quality.
- •Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.

■KYOCERA PART NUMBER

OPTION:

Above digits are used to track individual specification or thickness.

(Example) : CM Series(General) ①Series ②Size : 0201 ③ Dielectric

(4) Capacitance: 2.2 μF
(5) Tolerance: ±20%
(6) Voltage: 6.3 Vdc
(7) Termination: Sn
(8) Packaging: Cavity pitch 2mm / Reel Size φ180

(1) Series Code

CODE	Type
СМ	General
СТ	Low Profile
CU	High-Q
AR	Automotive
KNH	Three Terminal Capacitors

②Size Code

_				
CODE	EIA	JIS		
02	01005	0402		
03	0201	0603		
05	0402	1005 1608		
105	0603			
21	0805	2012		
316	1206	3216		
32	1210	3225		

③ Dielectric Code

Temperature Compensation Type						
CODE Temperature Range (°C) ppm/°C						
CG	-55 to 125 0		±30			
СН	-55 to 125	U	±60			

- All parts of COG will be marked as "CG" but will conform to the
- Temperature coefficients are determined by calculation based on measurement at 20°C and 85°C.

	High Dielectric Constant Type								
CODE	Temperature Range (°C)	Standard Temperature (°C)							
X5R	-55 to 85	±15							
X6S	-55 to 105	±22							
X6T	-55 10 105	+22/-33	25						
X7R		±15	23						
X7S	-55 to 125	±22							
X7T		+22/-33							

4 Capacitance Code

Capacitance expressed in pF. Two significant digits plus number of zeros. For Values < 10pF, Letter R denotes decimal point, 102=1,000pF=1nF (Example)

CODE	Capacitance
R50	0.5pF
1R0	1pF
100	10pF
101	100pF
102	1nF
103	10nF
104	100nF
105	1µF
106	10µF
107	100µF

(5) Tolerance Code

Temperature Compensation Type (C0G)						
CODE	Tolerance					
A*	±0.05pF					
В	±0.1pF					
С	±0.25pF ±0.5pF					
D						
G*	±2%					
J	±5%					
K	±10%					

^{*:} Option

High Dielectric Constant Type							
(X5R/X6	(X5R/X6S/X6T/X7R/X7S/X7T)						
CODE	CODE Tolerance						
J*	±5%						
K	±10%						
М	±20%						

^{*:} Option

6 Voltage Code

	3
CODE	Rated Voltage
02	2.5Vdc
04	4Vdc
06	6.3Vdc
10	10Vdc
16	16Vdc
25	25Vdc
35	35Vdc
50	50Vdc
100	100Vdc

7 Termination Code

CODE	Termination	
Α	Nickel Barrier/	Tin
• Please is need	contact us if Au termina led.	ation

Packaging Code

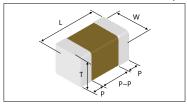
CODE	Size Code	Cavity pitch	Reel size
Т	105 to 32	4mm	
Н	02 to 05 2mm		φ180
Q	03/05	1mm	ψ100
Р	02	1mm	
L	105 to 32	4mm	
N	02 to 05	2mm	φ330
W	03/05	1mm	



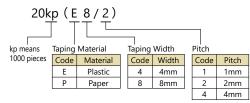


Dimension

■CM/CT/CU/AR Series (Two Terminal Capacitors)

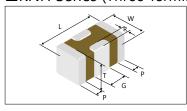


■Packaging Code



C:	Со	de	Dimension		Dimension (mm)						per reel
Size	EIA	JIS	Code	L	W	Т	P min.	P max.	P to P min.	φ180 Reel	φ330 Reel
02	01005	0402	А	0.4±0.02	0.2±0.02	0.2±0.02	0.07	0.14	0.13	40kp(E4/1) 20kp(P8/2)	_ 80kp (P8/2)
			A B	0.6±0.03	0.3±0.03	0.22 max. 0.3±0.03	0.1	0.2	0.2	30kp(P8/1) 15kp(P8/2)	150kp(P8/1) 50kp(P8/2)
03	0201	0603	С	0.6±0.05	0.3±0.05	0.3±0.05				13kp(F0/2)	30KP(F0/2)
03	0201	0003	D			0.22 max.	0.13	0.23	0.19	15kp (P8/2)	50kp (P8/2)
			E	0.6±0.09	0.3±0.09	0.3±0.09	0.13	0.23	0.13	· · · · · · · · · · · · · · · · · · ·	30κρ(10/2)
			F			0.5±0.05				10kp (P8/2)	_
			Α	1.0±0.05	0.5±0.05	0.33 max.				20kp(P8/1)	100kp(P8/1)
			В			0.5±0.05				10kp(P8/2)	50kp(P8/2)
			С	1.0±0.1	0.5±0.05	0.22 max.			0.3	10kp (P8/2)	50kp(P8/2)
		1005	D	1.0±0.15	0.5±0.15	0.5±0.15		0.35		10kp (P8/2)	40kp(P8/2)
05	0402		E	1.0±0.2	0.5±0.2	0.33 max.	0.15			10kp (P8/2)	_
			F			0.5 max.				10kp(P8/2)	50kp(P8/2)
			G H			0.55 max. 0.5±0.2				101(D0/2)	401(00/2)
			J				_			10kp(P8/2)	40kp(P8/2)
			-			0.8 max. 0.55 max.				10kp (P8/2)	30kp(P8/2)
			A B	1.6±0.1	0.8±0.1			0.6	0.5	4kp(P8/4)	10kp(P8/4)
105	0603	1608	С	1.6±0.15	0.8±0.15	0.8±0.1 0.8±0.15	0.2				
			D	1.6±0.13	0.8±0.13	0.8±0.13					
			A	2.0±0.1	1.25±0.1	1.25±0.1				3kp (E8/4)	10kp (E8/4)
			В	2.0±0.15	1.25±0.15	0.95 max.			-	•	·
21	0805	5 2012	С	2.0±0.13		0.95 max.	0.2	0.75	0.7	4kp (P8/4)	10kp (P8/4)
			D	2.0±0.2	1.25±0.2	1.25±0.2				3kp (E8/4)	10kp (E8/4)
			A	3.2±0.2	1.6±0.2	0.95 max.				4kp(P8/4)	-
			В	B 16+015	1.6±0.15	0.3	0.85	1.4	·	4	
316	1206	3216	С	3.2±0.2	1.6±0.2	1.6±0.2				2.5kp (E8/4)	5kp (E8/4)
			D	3.2±0.3	1.6±0.3	1.6±0.3	0.3	0.85	1.9	2kp(E8/4)	_
32	1210	3225	Α	3.2±0.3	2.5±0.2	2.5±0.2	0.3	1.0	1.4	1kp(E8/4)	4kp(E8/4)

■KNH Series (Three Terminal Capacitors)



Siz		Code Dimension					Packaging										
312	.e _	EIA	JIS	Code	L	W	T	G	Р	R	φ180 Reel	φ330 Reel					
KN	ш	0402	0402	0402	0402	A	Α	1.0±0.1	0.5±0.2	0.5 max.							
0						0402	0402	0402	0402	1005	В	1.0±0.15	0.5±0.15	0.5±0.15	0.3 ± 0.1	0.15±0.1	≥0.05
U.)				С	1.0±0.2	0.5±0.2	0.5±0.2									





High-Q CU Series

RoHS Compliant Products

■Features

Ultra-miniature size (0.4x0.2mm) Low loss characteristics suitable for high frequency

■Applications

RF power amplifier for mobiles such as impedance matching purpose.

Temperature Compensation Dielectric

Capacitance chart

Standard Spec.1

Size (EIA Code)		02 005)
Rated Voltage (Vdc) Capacitance	16	25
R20 0.2 pF R50 0.5 pF R50 1.5 pF 1R0 1 pF 1R5 1.5 pF 2R0 2 pF 3R0 3 pF 4R0 4 pF 5R0 6 pF 7R0 7 pF 8R0 8 pF 9R0 9 pF 100 10 pF 120 12 pF 150 15 pF 180 18 pF 220 22 pF 240 24 pF	A	A

Please contact for capacitance value other than standard.

Please refer to $\underline{\text{here}}$ for the test method and specifications of Standard Specification 1.

Alphabets in capacitance chart denote dimensions. Please refer to the below table for detail.

(Example) In case of "A" for CU02; L: 0.4 ± 0.02 mm, W: 0.2 ± 0.02 mm, T: 0.2 ± 0.02 mm

				imension (mr	~)					Pack	aging				
		D:	U	imension (mi	11)	φ180 Reel					Pitch Code Quantity Taping Width Pitch				
3	Size	Dimension Code	L	W	Т	Code	Quantity (pcs.)	Taping Material	Taping Width (mm)	Cavity Pitch (mm)	Code	-	, , ,	Width	Pitch
	02	٨	0.4±0.02	0.2±0.02	0.2±0.02	Р	40,000	Plastic	4	1	_	_	_	_	_
	02 A (A 0.4±0.02 0.2±0.02 0.2±0.02		Н	20,000	Paper	8	2	N	80,000	Paper	8	2		





Test Conditions and Standards

Test Conditions and Specifications for Temperature Compensation Type (C Δ Characteristics) CM / CT/ CU Series (Standard Spec.1)

Test	Items	Te	st Condi	itions (Complies w	Specifications				
Capacitance Va	lue (C)		Capacita		requency	Volt		Within tolerance		
Q		C≤1000pF 1MHz±10% 0.5 to 5Vrms C>1000pF 1kHz±10% 0.5 to 5Vrms					C≥30pF: Q≥1000 C<30pF: Q≥400+20C			
Insulation Resis	tance (IR)	and humidity	<i>/</i> .			ure it in norma itor must not e	•	Over $10000M\Omega$ or $500M\Omega$ • μ F, whichever is less		
Dielectric Resist	tance	*ĊÜ02C∆R20	-120/25V:	twice	ge for 1 to 5 se	econds. itor must not e	cceed 50mA.	No problem observed		
Appearance		Microscope						No problem observed		
Termination Str	ength	Apply a sidev note: 1N for 0		of 500g ((5N) to a PCB-r	mounted sampl	e.	No problem observed		
Bending Streng	th	Glass epoxy F	CB: Fulcrur	n spacin	g: 90mm, dura	tion time 10 sec	conds.	No significant damage with 1mm bending.		
Vibration Test	Appearance	Vibration free	uencv: 10	to 55 (H:	z)			No problem observed		
	Capacitance	Amplitude: 1.	5mm			V V 17 I	2	Within Tolerance		
	Q	hours each, 6			Hz/ 1 minute ii	n X, Y and Z dir	ections: 2	C≥30pF : Q≥1000 C<30pF : Q≥400+20C		
Soldering Heat	Appearance	Soak the sam	ple in 260°	C±5°C s	older for 10±0	.5 seconds and	place in nor-	No problem observed		
Resistant	Capacitance Variation		ure and hu	ımidity, a	and measure th	Within±2.5% or±0.25pF, whichever is larger				
	Q		Order 1		mperature) to 100°C	Time 2 minutes		C≥30pF : Q≥1000 C<30pF : Q≥400+20C		
	IR		2		0 to 200°C	2 minutes		Over $10000M\Omega$ or $500M\Omega \cdot \mu F$ whichever is less		
	Withstanding Voltage	The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.					Resist without problem			
Solderablity		Soaking cond	Sn-3Ag-0 Sn63 Solo		245±5°C 235±5°C	3±0.5 sec. 2±0.5 sec.		Solder coverage : 95% min.		
Temperature	Appearance							No problem observed		
Cycle	Capacitance Variation	(Cycle) Room tempe Lowest opera			80 min)→			Within±2.5% or ±0.25pF, whichever is larger		
	Q	Room tempe Highest oper	rature (3 m ation temp	in.)→ erature(3	30 min.)			C≥30pF: Q≥1000 C<30pF: Q≥400+20C		
	IR	After 5 cycles The charge a				itor must not e	ceed 50mA	Over $10000M\Omega$ or $500M\Omega$ • μ F, whichever is less		
	Withstanding Voltage				measurement.			Resist without problem		
Moisture	Appearance							No problem observed		
Resistant Load	Capacitance Variation	40°C±2°C and	d 90 to 95%	6RH, allo		0 hours in the or stabilize in nor		Within±7.5% or ±0.75pF, whichever is larger		
	Q		nd discharg			itor must not e	ceed 50mA	C≥30pF: Q≥200 C<30pF: Q≥100+10C/3		
	IR							Over $500M\Omega$ or $25M\Omega \cdot \mu F$, whichever is less		
High-	Appearance	After applyin	fter applying *twice the rated voltage in the temperature of 125±3°C		125±3°C	No problem observed.				
Temperature Load	Capacitance Variation	for 1000+12/ temperature	-0 hours, and humidi	measure ity.	the sample af	ter 24±2 hours	in normal	Within ±3% or ±0.3pF, whichever is larger		
	Q	for IR measur *Applied volt	ement.	•	·	tor must not ex ndicated in the	ceed 50mA	C≥30pF : Q≥350 10pF <c<30pf 2<br="" :="" q≥275+5c="">C<10pF : Q≥200+10C</c<30pf>		
	IR	Citait DelOW.	chart below.					Over $1000M\Omega$ or $50M\Omega$ • μ F, whichever is less		

Please ask for individual specification for the hatched range in previous chart.

Voltage to be applied in the High Temperature Load (Applied voltage is the multiple of the rated volatage)

A	Applied Voltage	Rated Voltage	Products
Г	×1.0	16V	CM02CA221
	×1.2	25V	CM02C∆R20-120

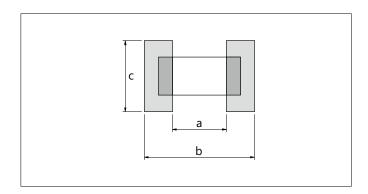




Test Conditions and Standards

Substrate for Adhesion Strength Test, Vibration Test, Soldering Heat Resistance Test, Temperature Cycle Test, Load Humidity Test, High-Temperature with Loading Test.

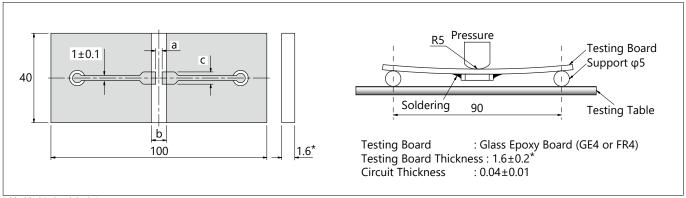
(Unit: mm)



Size (EIA Code)	a	b	С
02 (01005)	0.15	0.5	0.2
03 (0201)	0.26	0.92	0.32
05 (0402)	0.4	1.4	0.5
105 (0603)	1.0	3.0	1.2
21 (0805)	1.2	4.0	1.65
316 (1206)	2.2	5.0	2.0
32 (1210)	2.2	5.0	2.9

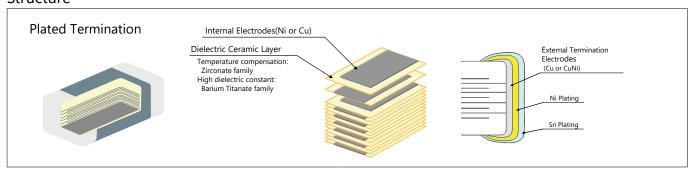
Substrate for Bending Test

(Unit: mm)



* 02, 03, 05 size 0.8±0.1mm

Structure



■Certification status

<ISO>

Acquired ISO 9001 quality management system certification.

<IATF>

Acquired IATF 16949 quality management system certification.

■Production plant

Kagoshima kokubu plant

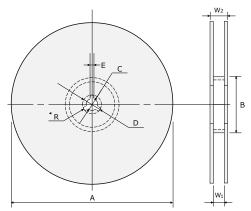


KYOCERa

(Unit: mm)

Packaging Options Tape and Reel

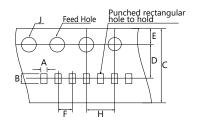


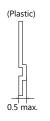


Code Reel	А	В	С	D	
7-inch Reel (CODE: T, H, Q)	180 +0				
7-inch Reel (CODE: P)	178±2.0	φ60 min.	13±0.5	21±0.8	
13-inch Reel (CODE: L, N, W)	330±2.0				
Code Reel	E	W 1	W2	R	
7-inch Reel (CODE: T, H, Q)		10.5±1.5	16.5 max.		
7-inch Reel (CODE: P)	2.0±0.5	4.35±0.3	6.95±1.0	1.0	
13-inch Reel (CODE: L, N, W)		9.5±1.0	16.5 max.		

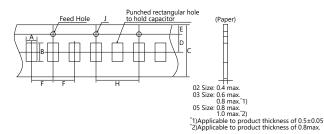
Carrier Tape (Unit: mm)

F=1mm (02 Size)



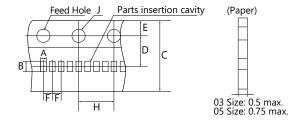


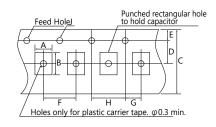
F=2mm (02, 03, 05 Size)

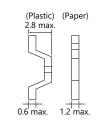


F=4mm (105, 21, 316, 32 Size)

F=1mm (03, 05 Size)







(Unit: mm)

Size	Α	В	С	D	Е	F	G	Н		Carrie	r Tape
(EIA Code)	^	В			_		6	П	,	Width	Material
02 (01005)*	0.24±0.02	0.44±0.02	4.0±0.08	1.8±0.02	0.9±0.05	1.0±0.02		2.0±0.04	0.8±0.04	4	Plastic
02 (01003)	0.25±0.03 0.45±0.03	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05		4.0±0.1	1.5+0.1/-0	8	Paper	
	0.37±0.03	0.67±0.03	8.0+0.3/-0.1	3.5±0.05	1.75±0.1	1.0±0.05		4.0±0.05	1.5+0.1/-0		
	0.57 ± 0.05	0.07 ± 0.03	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0		
03 (0201)*	0.39±0.03	0.69±0.03	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0	8	Paper
	0.42±0.03	0.72±0.03	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0		
	0.44±0.05 0	0.74±0.05	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0		
	0.65±0.1	8.0+0.3/-0.1			1.0±0.05	_	4.0±0.05]			
05 (0402)*	0.03±0.1	1.15±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	.05 — 4.0±		1.5+0.1/-0	8	Paper
03 (0402)	0.75±0.1		0.0±0.3			2.0±0.03		4.0±0.1			rapei
	0.8±0.1	1.3±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	_	4.0±0.1	1.5+0.1/-0		
105 (0603)*	1.0±0.2	1.8±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8	Paper
103 (0003)	1.1±0.2	1.9±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	0	Гарсі
21 (0805)	1.5±0.2	2.3±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8	Paper
21 (0003)	1.5±0.2	2.3±0.2	0.0±0.3	3.3±0.03	1.73±0.1	4.0±0.1	2.0±0.03	4.0±0.1	1.5+0.1/-0	8	Plastic
316 (1206)	2.0±0.2	3.6±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8	Paper
310 (1200)	2.0±0.2	3.0±0.2	0.0±0.3	3.5±0.05		4.010.1	2.0±0.03	4.0±0.1	1.5+0.1/-0	8	Plastic
32 (1210)	2.9±0.2	3.6±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	8	Plastic

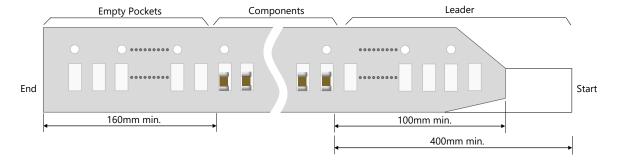
^{*} Option





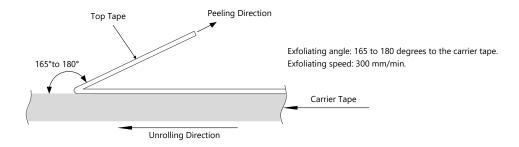
Packaging Options

Detail of leader and trailer



Adhesive tape

- 1) The exfoliative strength when peeling off the top tape from the carrier tape by the method of the following figure shall be *0.1 to 0.7N. *02 Size: 0.1 to 0.5N
- 2) When the top tape is peeled off, the adhesive stays on the top tape.
- 3) Chip capacitors will be in a state free without being stuck on the thermal adhesive tape.



Carrier tape

- 1) Chip will not fall off from carrier tape or carrier tape will not be damaged by bending than within a radius of 25mm.
- 2) The chip are inserted continuously without any empty pocket.
- 3) Chip will not be mis-mounted because of too big clearance between components and cavity. Also the waste of carrier tape will not fill a nozzle hole of mounting machine.



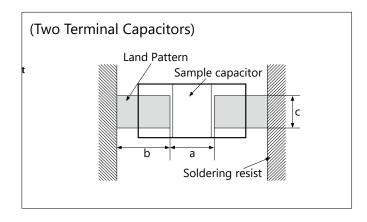


Surface Mounting Information

Dimensions for recommended typical land

Since the amount of solder (size of fillet) to be used has direct influence on the capacitor after mounting, the sufficient consideration is necessary.

When the amounts of solder is too much, the stress that a capacitor receives becomes larger. It may become the cause of a crack in the capacitor. When the land design of printed wiring board is considered, it is necessary to set up the form and size of land pattern so that the amount of solder is suitable.



Two Terminal Capacitors

(Unit: mm)

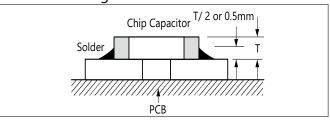
Size	Dime	nsion	Recommended land dimensions					
(EIA Code)	L	W	а	b	С			
02 (01005)	0.4±0.02	0.2±0.02	0.13 to 0.2	0.12 to 0.18	0.2 to 0.23			
	0.6±0.03	0.3±0.03	0.2 += 0.25	0.25 += 0.25	02+004			
03 (0201)	0.6±0.05	0.3±0.05	0.2 to 0.25	0.25 to 0.35	0.3 to 0.4			
	0.6±0.09	0.3±0.09	0.23 to 0.3	0.25 to 0.35	0.3 to 0.45			
	1.0±0.05	0.5±0.05	0.3 to 0.5	0.35 to 0.45	0.4 to 0.6			
05 (0402)	1.0±0.15	0.5±0.15	0.4 to 0.6	0.4 to 0.5	0.5 to 0.75			
	1.0±0.2	0.5±0.2	0.4 10 0.6	0.4 10 0.5	0.5 to 0.75			
	1.6±0.1	0.8±0.1	0.7 to 1.0	0.8 to 1.0	0.6 to 0.9			
105 (0603)	1.6±0.15	0.8±0.15						
103 (0003)	1.6±0.2	0.8 ± 0.2	0.8 to 1.0	0.8 to 1.0	0.8 to 1.1			
	1.6±0.25	0.8±0.25						
	2.0±0.1	1.25±0.1	1.0 to 1.3	1.0 to 1.2	1.0 to 1.45			
21 (0805)	2.0±0.15	1.25±0.15	1.0 to 1.3	1.0 to 1.2	1.25 to 1.55			
	2.0±0.2	1.25±0.2	1.0 to 1.3	1.0 to 1.2	1.23 (0 1.33			
	3.2±0.2	1.6±0.15	2.1 to 2.5	1.1 to 1.3	1.4 to 1.9			
316 (1206)	3.2±0.2	1.6±0.2	2.1 to 2.5	1.1 to 1.3	1.6 to 2.0			
	3.2±0.3	1.6±0.3	2.1 (0 2.3	1.1 (0 1.5	1.0 10 2.0			
32 (1210)	3.2±0.3	2.5±0.2	2.1 to 2.5	1.1 to 1.3	1.9 to 2.8			

^{*} Recommended land dimensions may differ depending on dimensional tolerance.

Design of printed circuit and Soldering

The recommended fillet height shall be 1/2 of the thickness of capacitors or 0.5mm. When mounting two or more capacitors in the common land, it is necessary to separate the land with the solder resist strike so that it may become the exclusive land of each capacitor.

Ideal Solder Height



14	Durch it is a d	B
Item	Prohibited	Recommended example : Separation by solder resist
Multiple parts mount		Solder resist
Mount with leaded parts	Leaded parts	Solder resist Leaded parts
Wire soldering after mounting	Soldering iron Wire	Solder resist
Side by side layout	Solder resist	Solder resist



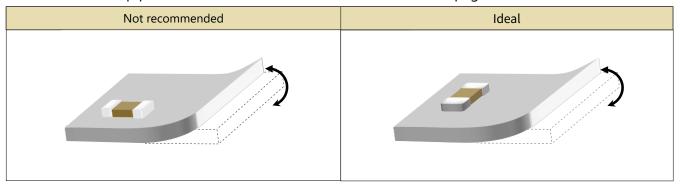


Surface Mounting Information

Mounting Design

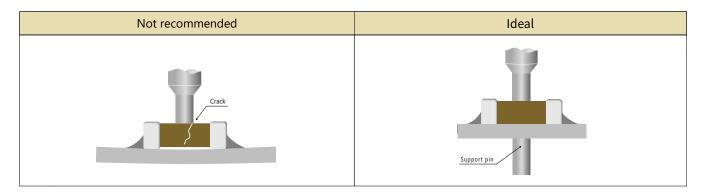
The chip could crack if the PCB warps during processing after the chip has been soldered.

Recommended chip position on PCB to minimize stress from PCB warpage



Actual Mounting

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 1 to 3 N.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.
- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.



Resin Mold

- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.





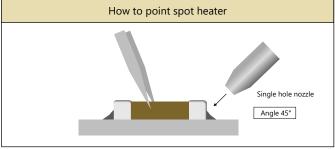
Surface Mounting Information

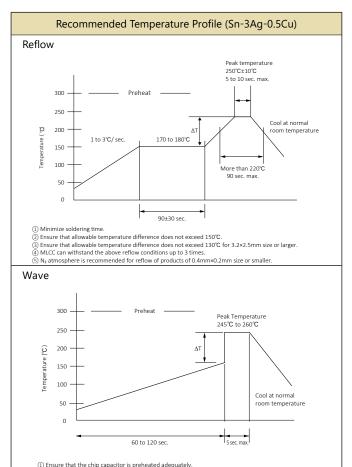
Soldering Method

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 150 degree Celsius.
- 2) The product size 1.6×0.8mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of bigger than 3.2×1.6mm, or smaller than 1.6×0.8mm can be used in reflow.

 Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
- 4) In case of using Sn-Zn Solder, please contact us in advance.
- 5) The following condition is recommended for spot heater application.
- Recommended spot heater condition

Item	Condition
Distance	5mm min.
Angle	45°
Projection Temp.	400°C max.
Flow rate	Set at the minimum
Nozzle diameter	2φ to 4φ (Single hole type)
Application time	10 sec. max. (1206 and smaller) 30 sec. max. (1210 and larger)



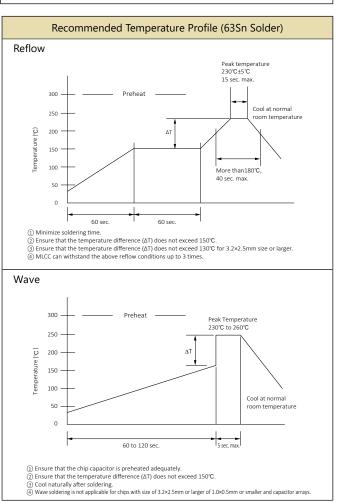


© Ensure that the time popularis is premated adequately.

2 Ensure that the temperature difference (AT) does not exceed 150°C.

3 Cool naturally after soldering.

4 Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays.





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Precautions

Circuit Design

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.

 Accident or malfunction of devices such as medical devices, space equipment and devices having to do with

Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.

3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.

Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.

The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.

When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.

- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage. In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
 Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer. In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising

pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.

voltage or, in worst case situations, may cause the capacitor to smoke or flame.

- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

 Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications. In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

Storage

Please note the following regarding the storage of delivered products.

- 1. Set the storage temperature to + 5 to + 40 $^{\circ}$ C and humidity to 20 ~ 70% RH. Other meteorological conditions are in accordance with classification 1 K2 of JIS C 60721 -3 -1.
- 2. Store in a place where corrosive gas (H₂S, SO₂, NO₂, Cl₂, etc.) does not exist in the atmosphere. Also, avoid exposure to salty moisture. In either case, this may cause oxidation corrosion of the terminal electrode, reducing solderability.

If you store the above delivered products according to the conditions listed above, it will satisfy the solderability standard for 6 months from the shipping date.

Safety application guideline and detailed information of electrical properties are also provided in kyocera web site; URL: https://ele.kyocera.com/en/product/capacitor/





Part Number List



High-Q CU02 Series Size (JIS Code): 01005(0402) # Packaging Code (Packaging quantity): H(20,000pcs.) / N(80,000pcs.) / P(40,000pcs.)

Dielectric code			Voltage				Dimension		# Packaging
CΔ	Capacitance	□:Tolerance	[V]	Part Number	Q	L[mm]	W[mm]	T[mm]	Code (quantity)
	0.2pF		25	CU02CΔR20□25A#	404	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	0.2pr		16	CU02CΔR20□16A#	404	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	0.5pF		25	CU02CΔR50□25A#	410	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	0.5pr		16	CU02CΔR50□16A#	410	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	1pF		25	CU02CΔ1R0□25A#	420	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	ipr		16	CU02CΔ1R0□16A#	420	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	1 EnF		25	CU02CΔ1R5□25A#	430	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	1.5pF	B:±0.1pF / C:±0.25pF	16	CU02CΔ1R5□16A#	430	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	255		25	CU02CΔ2R0□25A#	440	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	2pF		16	CU02CΔ2R0□16A#	440	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	3pF		25	CU02CΔ3R0□25A#	460	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	3pr		16	CU02CΔ3R0□16A#	460	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	4		25	CU02CΔ4R0□25A#	480	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	4pF		16	CU02CΔ4R0□16A#	480	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	F.F		25	CU02CΔ5R0□25A#	500	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
CG/CH	5pF		16	CU02CΔ5R0□16A#	500	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
CG/CH	6pF		25	CU02CΔ6R0□25A#	520	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	брғ		16	CU02CΔ6R0□16A#	520	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	7.5		25	CU02CΔ7R0□25A#	540	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	7pF	6035.5 (505.5	16	CU02CΔ7R0□16A#	540	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	0.5	C:±0.25pF / D:±0.5pF	25	CU02CΔ8R0□25A#	560	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	8pF		16	CU02CΔ8R0□16A#	560	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	0.5		25	CU02CΔ9R0□25A#	580	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	9pF		16	CU02CΔ9R0□16A#	580	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	40.5		25	CU02CΔ100□25A#	600	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	10pF		16	CU02CΔ100□16A#	600	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	12.5		25	CU02CΔ120□25A#	640	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	12pF	L F0/ / K 100/	16	CU02CΔ120□16A#	640	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	15pF	J:±5% / K:±10%		CU02CΔ150□16A#	700	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	18pF		1.0	CU02CΔ180□16A#	760	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	22pF		16	CU02CΔ220□16A#	840	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P
	24pF		1	CU02CΔ240□16A#	880	0.4±0.02	0.2±0.02	0.2±0.02	H/N/P





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